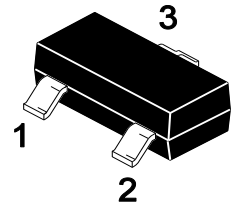




PJM3400NSA

N- Enhancement Mode Field Effect Transistor

SOT-23



1. Gate 2. Source 3. Drain

Marking: R0

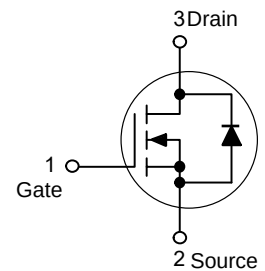
Features

- $V_{DS} = 30V, I_D = 5.8A$
 $R_{DS(ON)} < 59m\Omega @ V_{GS}=2.5V$
 $R_{DS(ON)} < 45m\Omega @ V_{GS}=4.5V$
 $R_{DS(ON)} < 41m\Omega @ V_{GS}=10V$
- High power and current handling capability

Applications

- Load switch and in PWM applications
- Power management

Schematic diagram



Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	5.8	A
Drain Current-Pulsed ^{Note1}	I_{DM}	30	A
Maximum Power Dissipation	P_D	0.9	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristics

Thermal Resistance, Junction-to-Ambient ^{Note2}	$R_{\theta JA}$	139	°C/W
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**Electrical Characteristics**(T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage ^{Note3}	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.7	0.9	1.4	V
Drain-Source On-State Resistance ^{Note3}	R _{DS(ON)}	V _{GS} =2.5V, I _D =4A	-	45	59	mΩ
		V _{GS} =4.5V, I _D =5A	-	31	45	mΩ
		V _{GS} =10V, I _D =5.8A	-	28	41	mΩ
Forward Transconductance ^{Note3}	g _{FS}	V _{DS} =5V,I _D =5A	10	-	-	S
Dynamic Characteristics						
Input Capacitance	C _{ISS}	V _{DS} =15V,V _{GS} =0V, f=1.0MHz	-	820	-	pF
Output Capacitance	C _{OSS}		-	99	-	pF
Reverse Transfer Capacitance	C _{RSS}		-	77	-	pF
Switching Characteristics						
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V, R _L =2.7Ω V _{GS} =10V,R _{GEN} =3Ω	-	3.3	-	nS
Turn-on Rise Time	t _r		-	4.8	-	nS
Turn-Off Delay Time	t _{d(off)}		-	26	-	nS
Turn-Off Fall Time	t _f		-	4	-	nS
Total Gate Charge	Q _g	V _{DS} =15V,I _D =5.8A, V _{GS} =4.5V	-	9.5	-	nC
Gate-Source Charge	Q _{gs}		-	1.5	-	nC
Gate-Drain Charge	Q _{gd}		-	3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^{Note3}	V _{SD}	V _{GS} =0V,I _S =5.8A	-	-	1.2	V
Diode Forward Current ^{Note2}	I _S		-	-	5.8	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.



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Typical Characteristics Curves

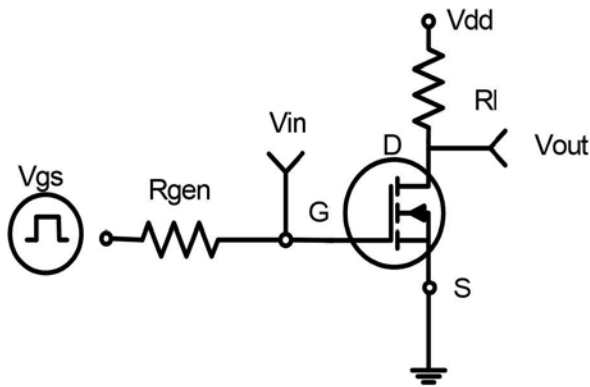


Figure 1: Switching Test Circuit

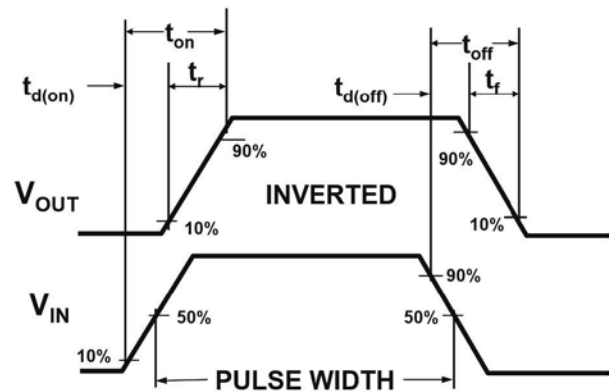
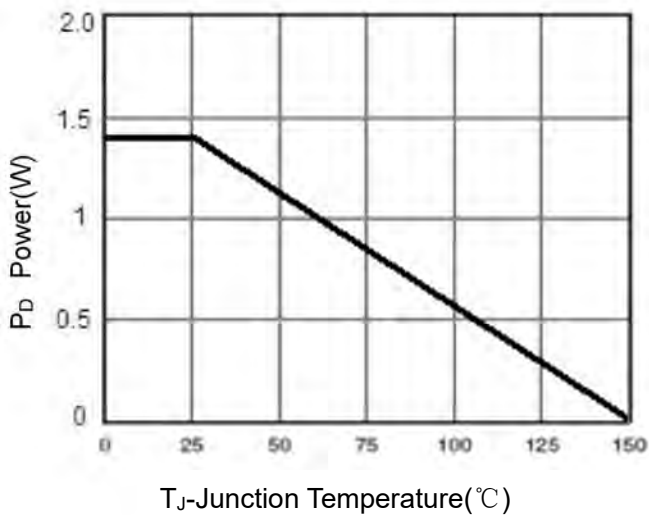
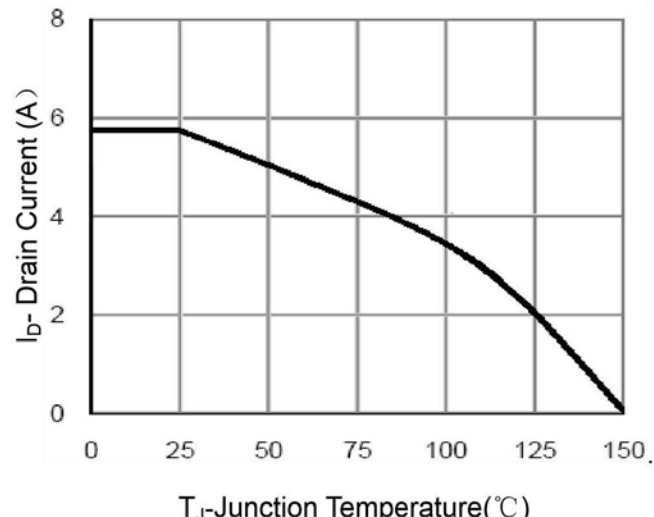


Figure 2: Switching Waveforms



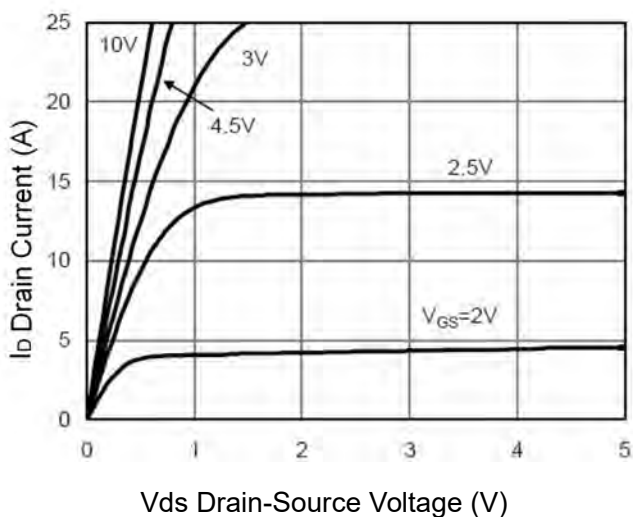
T_J-Junction Temperature(°C)

Figure 3 Power Dissipation



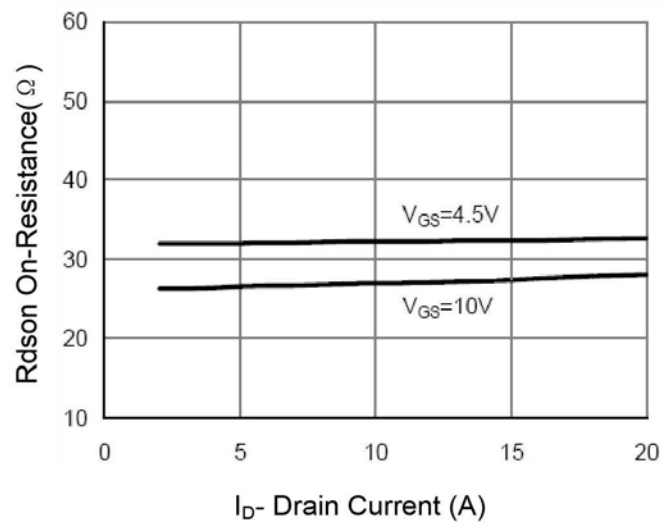
T_J-Junction Temperature(°C)

Figure 4 Drain Current



V_{ds} Drain-Source Voltage (V)

Figure 5 Output Characteristics



I_D- Drain Current (A)

Figure 6 Drain-Source On-Resistance



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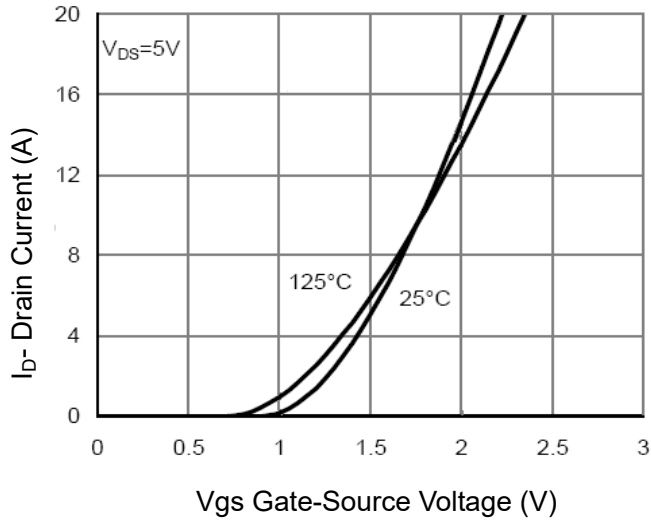


Figure 7 Transfer Characteristics

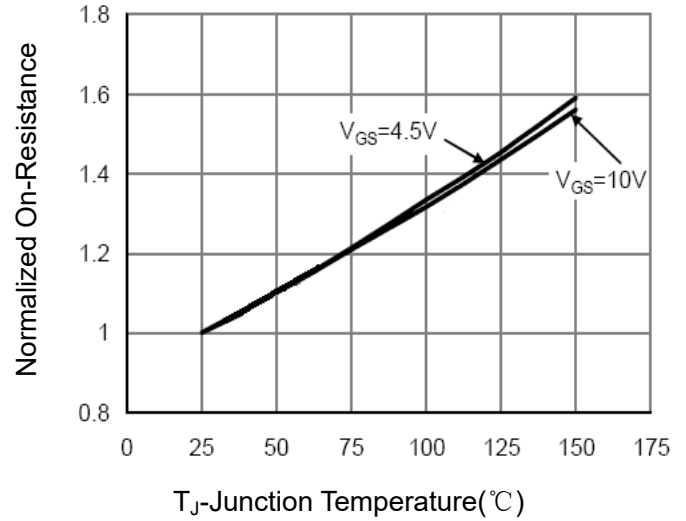


Figure 8 Drain-Source On-Resistance

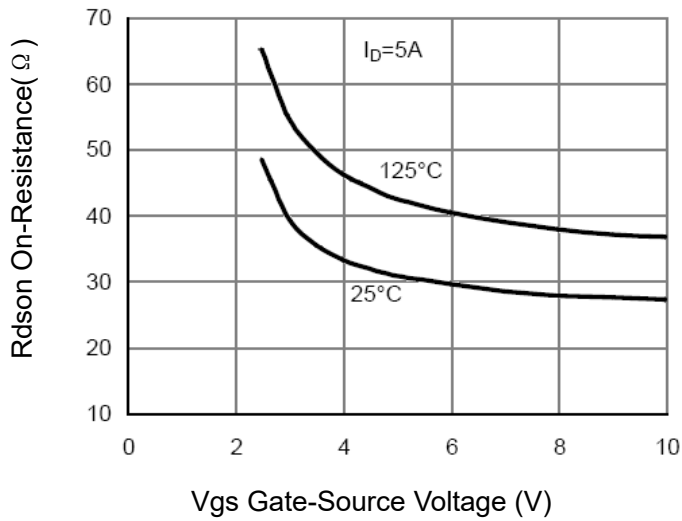


Figure 9 $R_{DS(on)}$ vs V_{GS}

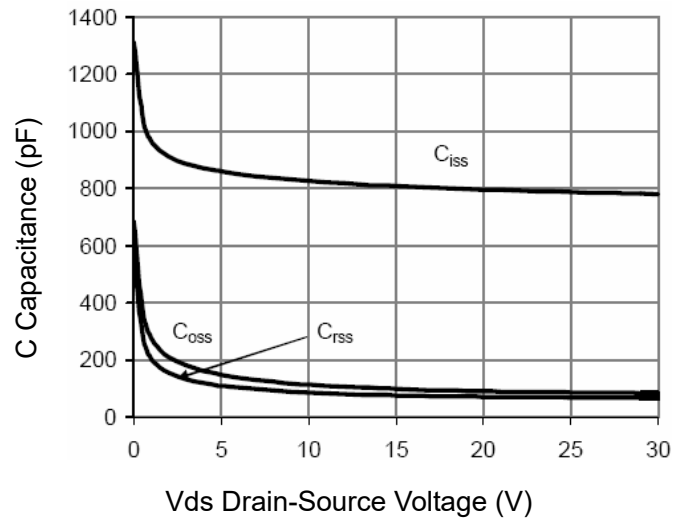


Figure 10 Capacitance vs V_{DS}

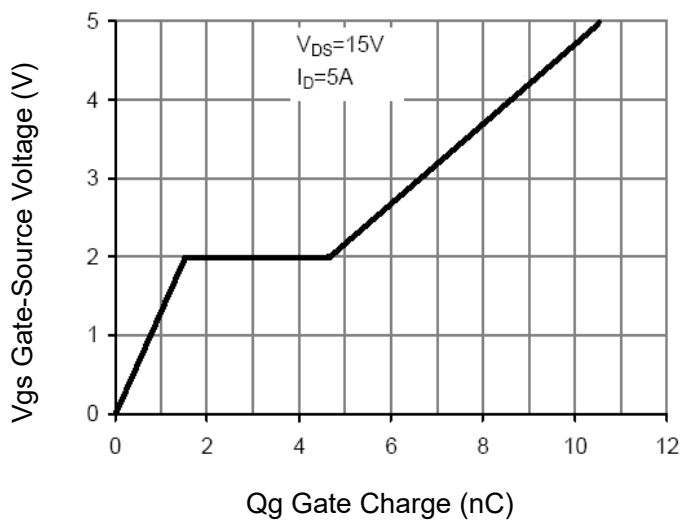


Figure 11 Gate Charge

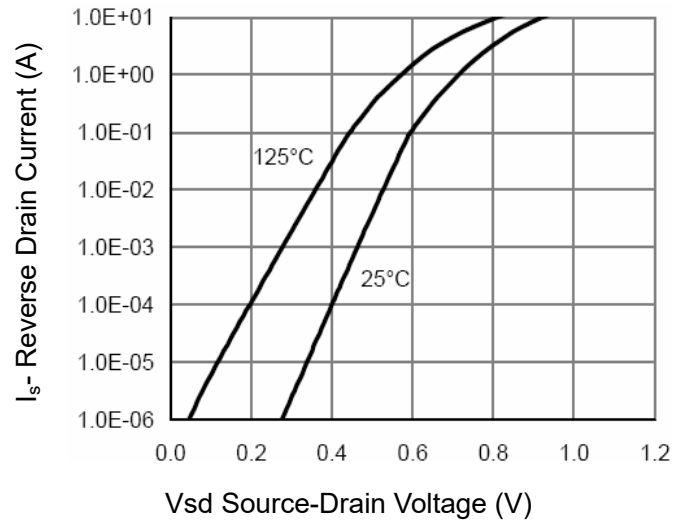


Figure 12 Source- Drain Diode Forward

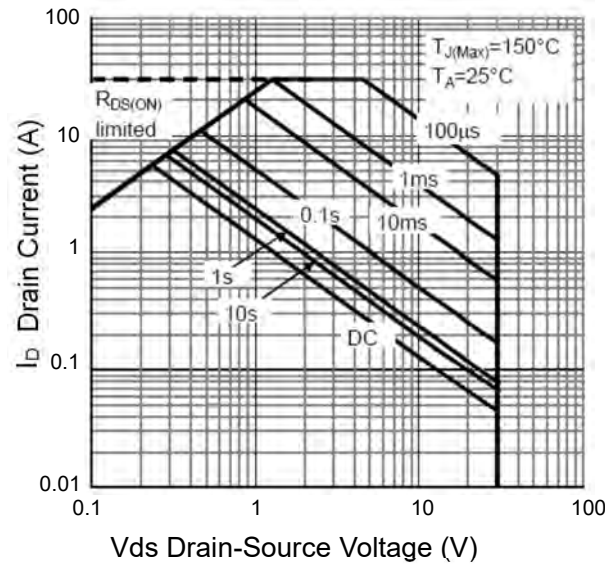


Figure 13 Safe Operation Area

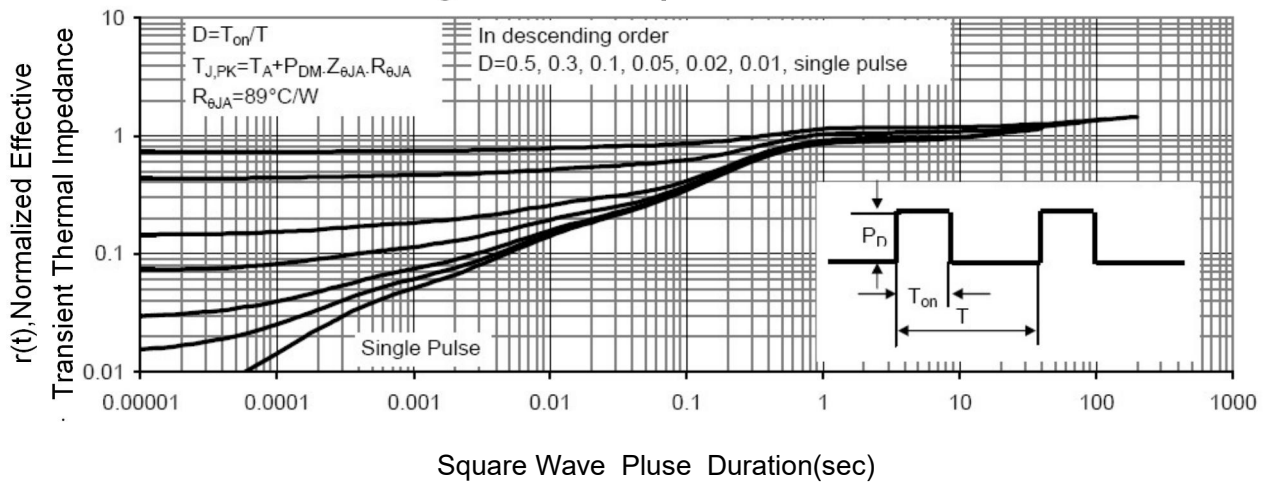


Figure 14 Normalized Maximum Transient Thermal Impedance

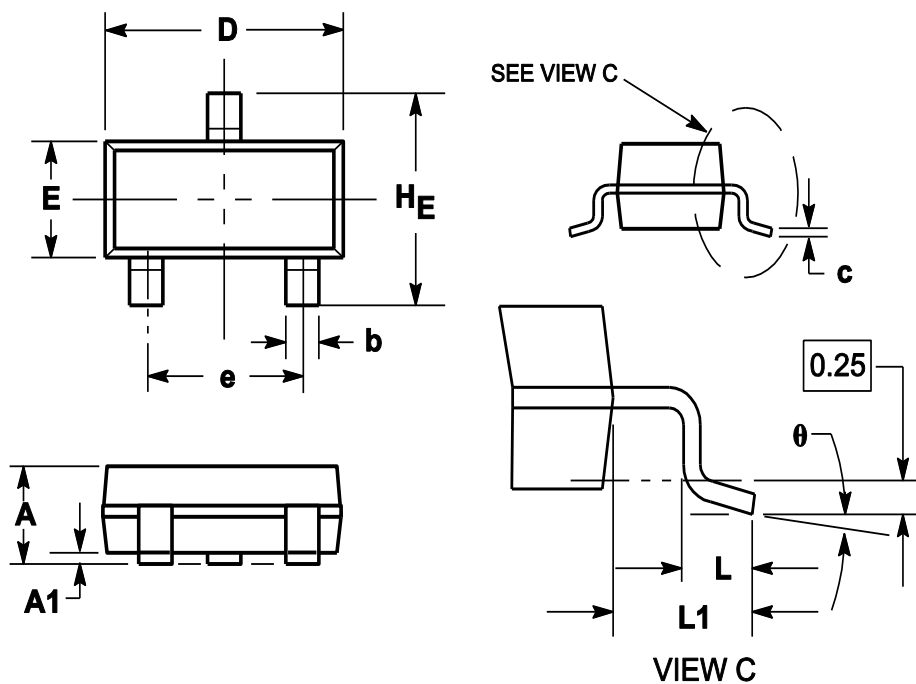


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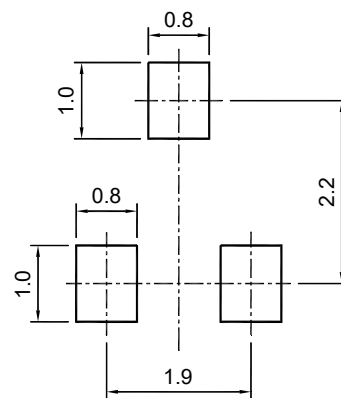
N- Enhancement Mode Field Effect Transistor

Package Outline

SOT-23



Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.900	1.025	1.150
A1	0.000	0.050	0.100
b	0.300	0.400	0.500
c	0.080	0.115	0.150
D	2.800	2.900	3.000
E	1.200	1.300	1.400
HE	2.250	2.400	2.550
e	1.800	1.900	2.000
L1	0.550REF		
L	0.300		0.500
θ	0°		8°



SOT-23 (TO-236)

Recommended Soldering Pad

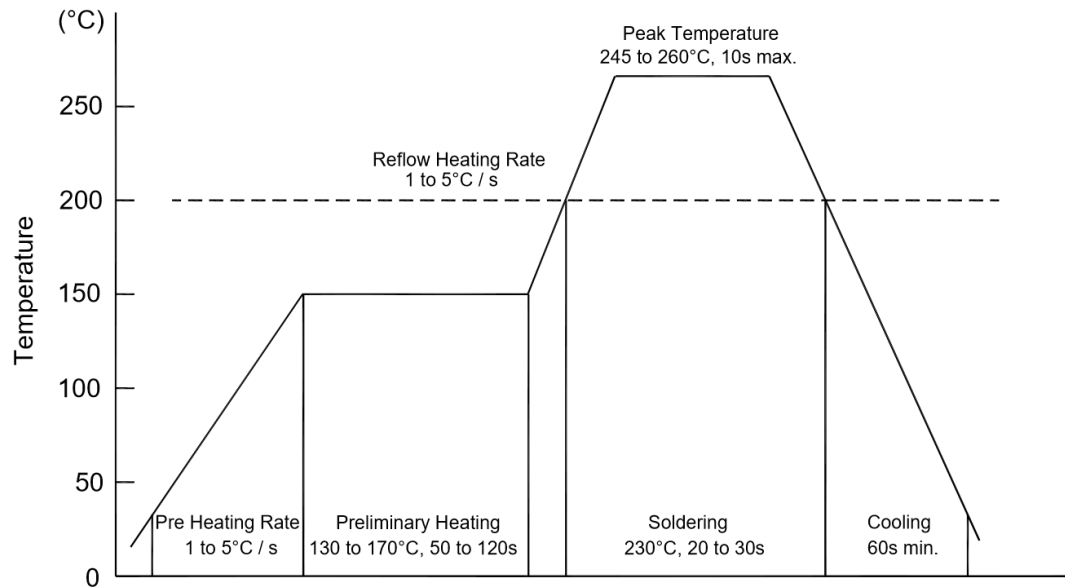
Ordering Information

Device	Package	Shipping
PJM3400NSA	SOT-23	3000/Reel&Tape(7inch)



Conditions of Soldering and Storage

◆ Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

◆ Conditions of hand soldering

- Temperature: 370 °C
- Time: 3s max.
- Times: one time

◆ Storage conditions

- **Temperature**
5 to 40 °C
- **Humidity**
30 to 80% RH
- **Recommended period**
One year after manufacturing

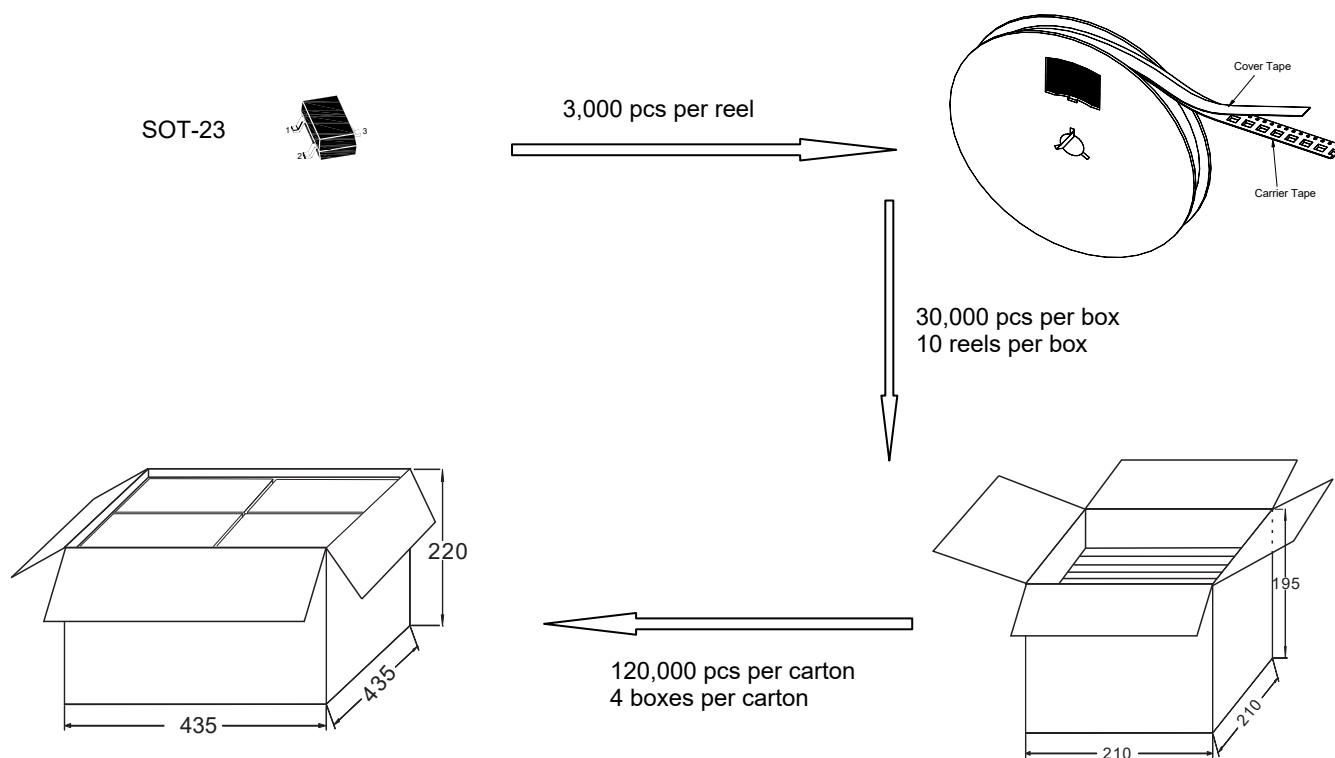


PJM3400NSA

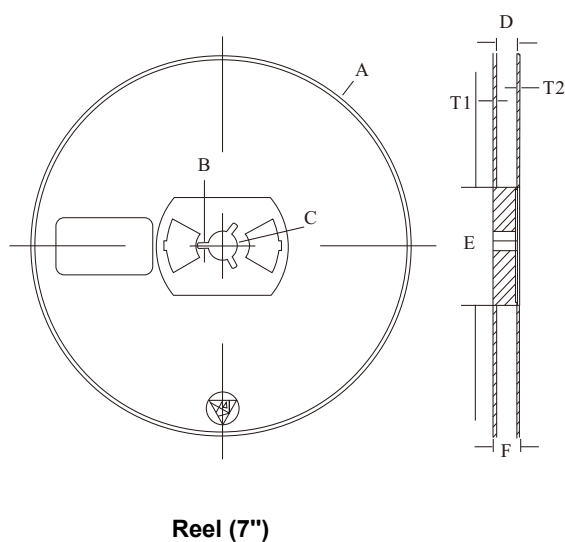
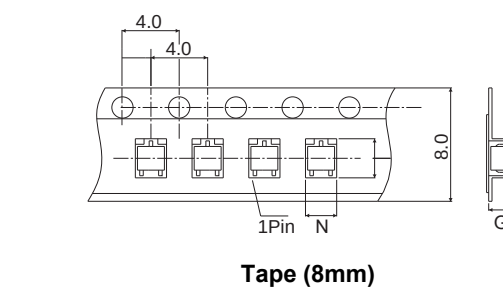
N- Enhancement Mode Field Effect Transistor

Package Specifications

◆ The method of packaging



◆ Embossed tape and reel data



Symbol	Value (unit: mm)
A	$\varnothing 177.8 \pm 1$
B	2.7 ± 0.2
C	$\varnothing 13.5 \pm 0.2$
E	$\varnothing 54.5 \pm 0.2$
F	12.3 ± 0.3
D	$9.6 + 2 / - 0.3$
T1	1.0 ± 0.2
T2	1.2 ± 0.2
N	3.15 ± 0.1
G	1.25 ± 0.1